



US00D756942S

(12) **United States Design Patent**  
**Shi et al.**

(10) **Patent No.:** **US D756,942 S**

(45) **Date of Patent:** **\*\* May 24, 2016**

(54) **LIGHT-EMITTING DIODE PACKAGE**

(71) Applicant: **XIAMEN SANAN OPTOELECTRONICS TECHNOLOGY CO., LTD.**, Xiamen (CN)

(72) Inventors: **Junpeng Shi**, Xiamen (CN); **Pei-Song Cai**, Xiamen (CN); **Zhenduan Lin**, Xiamen (CN); **Hao Huang**, Xiamen (CN)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/526,620**

(22) Filed: **May 12, 2015**

(30) **Foreign Application Priority Data**

May 6, 2015 (CN) ..... 2015 3 0129449

(51) **LOC (10) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/180**

(58) **Field of Classification Search**

USPC ..... D13/180; D26/1  
CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;  
H01L 27/156; H01L 31/02; H01L 33/00;  
H01L 33/04; H01L 33/08; H01L 33/10;  
H01L 33/20; H01L 33/38; H01L 33/42;  
H01L 33/48; H01L 33/62; H01L 33/483;  
H01L 33/486; F21K 9/00; F21K 9/30; F21K  
9/54

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D476,961 S \* 7/2003 Horiuchi ..... D13/182  
6,657,238 B2 \* 12/2003 Ueda ..... H01L 33/38  
257/100  
6,734,536 B2 \* 5/2004 Kobayakawa ..... H01L 21/4828  
257/676

(Continued)

*Primary Examiner* — Selina Sikder

(74) *Attorney, Agent, or Firm* — Syncoda LLC; Feng Ma; Junjie Feng

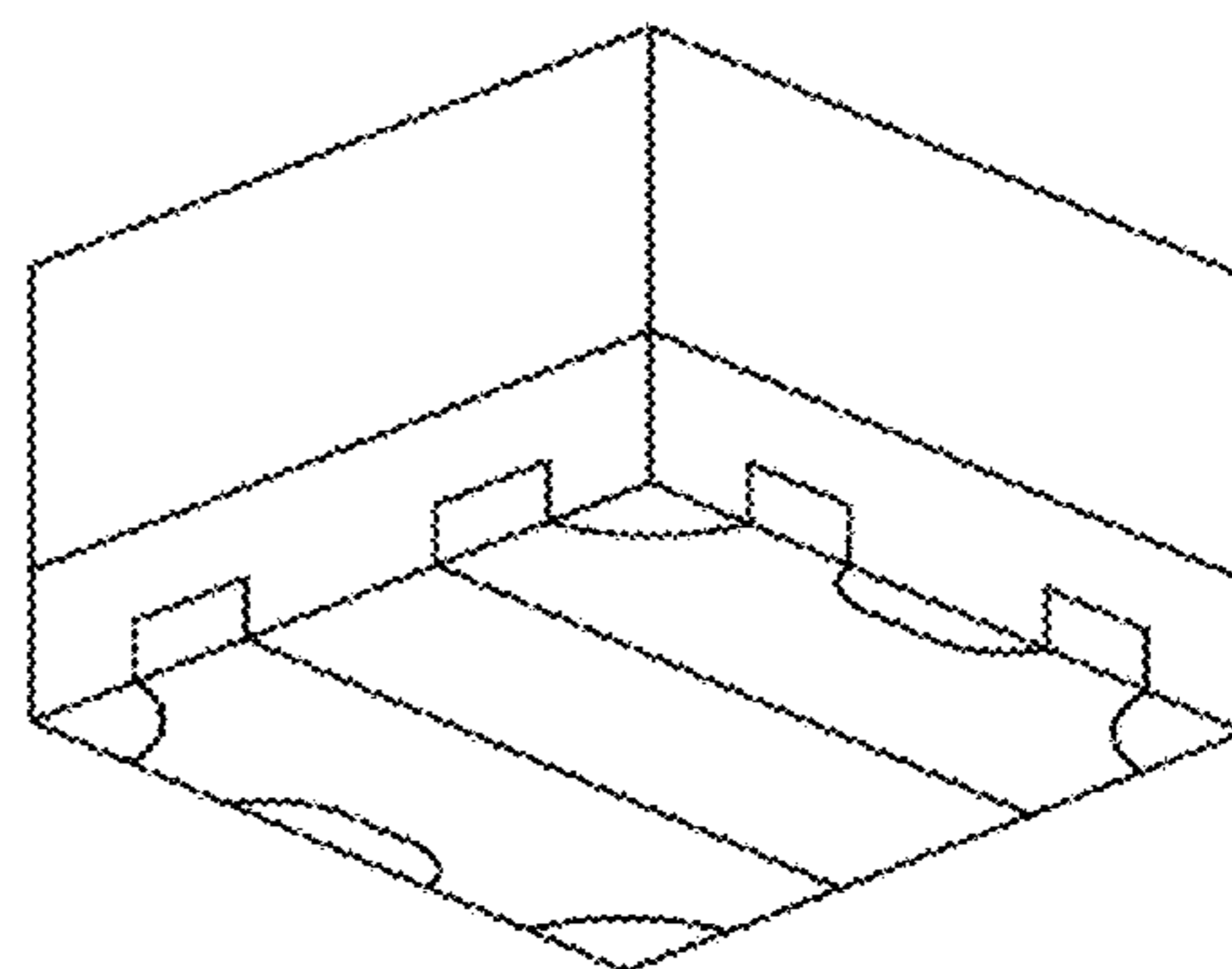
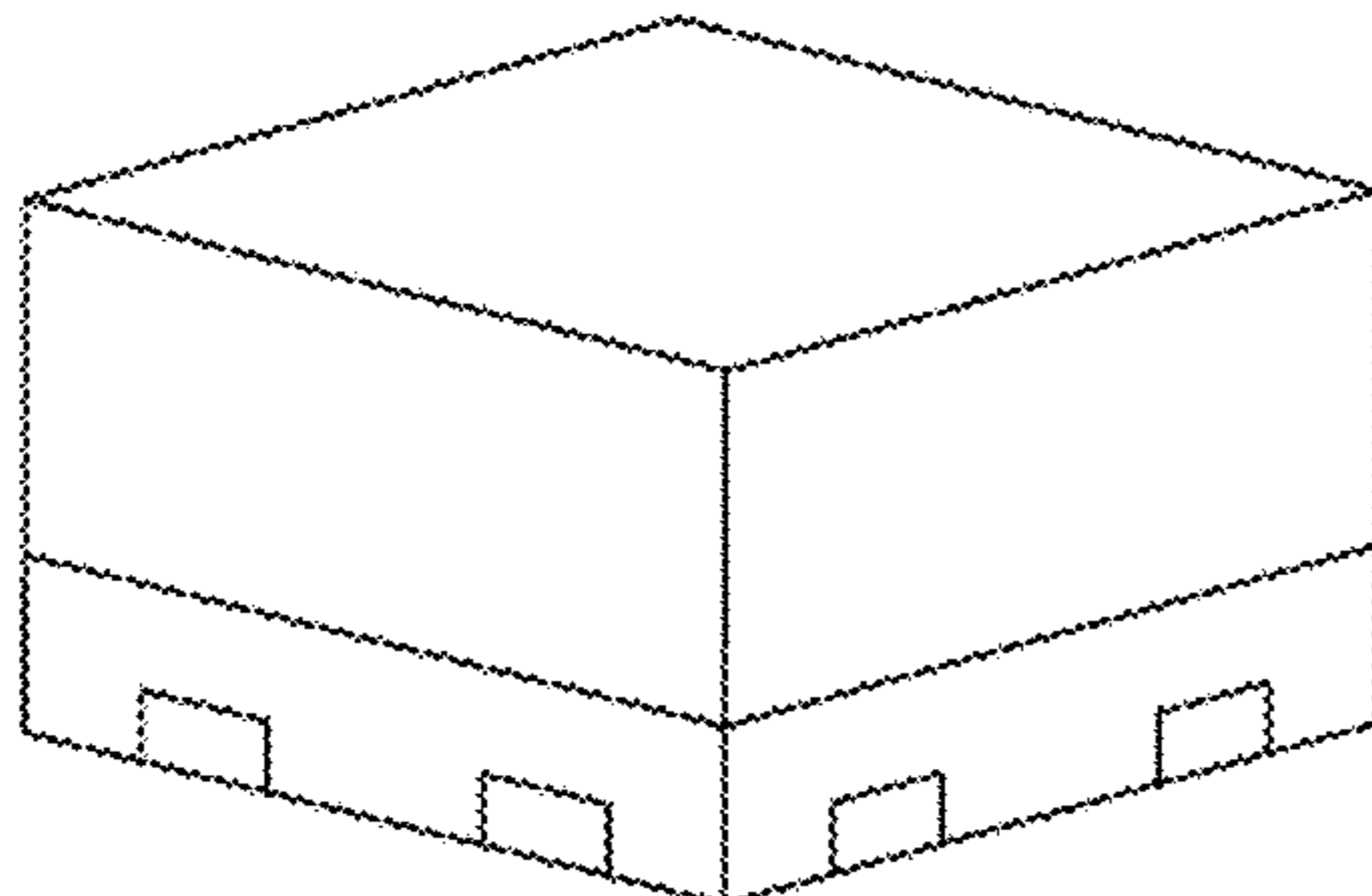
(57) **CLAIM**

The ornamental design for a light-emitting diode package, substantially as shown and described.

**DESCRIPTION**

FIG. 1 is a front view of a light emitting diode package according to a first embodiment of the disclosure; FIG. 2 is a rear view of a light emitting diode package according to the first embodiment of the disclosure; FIG. 3 is a left side view of a light emitting diode package according to the first embodiment of the disclosure; FIG. 4 is a right side view of a light emitting diode package according to the first embodiment of the disclosure; FIG. 5 is a top view of a light emitting diode package according to the first embodiment of the disclosure; FIG. 6 is a bottom view of a light emitting diode package according to the first embodiment of the disclosure; FIG. 7 is a perspective view of a light emitting diode package according to the first embodiment of the disclosure; FIG. 8 is another perspective view of a light emitting diode package according to the first embodiment of the disclosure; FIG. 9 is a front view of a light emitting diode package according to a second embodiment of the disclosure; FIG. 10 is a rear view of a light emitting diode package according to the second embodiment of the disclosure; FIG. 11 is a left side view of a light emitting diode package according to the second embodiment of the disclosure; FIG. 12 is a right side view of a light emitting diode package according to the second embodiment of the disclosure; FIG. 13 is a top view of a light emitting diode package according to the second embodiment of the disclosure; FIG. 14 is a bottom view of a light emitting diode package according to the second embodiment of the disclosure; FIG. 15 is a perspective view of a light emitting diode package according to the second embodiment of the disclosure; and, FIG. 16 is another perspective view of a light emitting diode package according to the second embodiment of the disclosure.

**1 Claim, 6 Drawing Sheets**



(56)

**References Cited**

U.S. PATENT DOCUMENTS

7,491,977	B2 *	2/2009	Fukasawa	.....	H01L 33/60				
					257/81				
7,586,178	B2 *	9/2009	Manatad	.....	H01L 23/49844				
					257/666				
D626,097	S *	10/2010	Takeuchi	.....	D13/180				
D626,922	S *	11/2010	Wada	.....	D13/180				
D629,767	S *	12/2010	Shimizu	.....	D13/180				
D671,509	S *	11/2012	Moriguchi	.....	D13/180				
D676,002	S *	2/2013	Watanabe	.....	D13/180				
D676,003	S *	2/2013	Takeda	.....	D13/180				
D694,201	S *	11/2013	Iino	.....	D13/180				
D698,742	S *	2/2014	Niikura	.....	D13/180				
D731,989	S *	6/2015	Huang	.....	D13/180				
D742,554	S *	11/2015	Kanemaru	.....	D26/1				
2002/0123163	A1 *	9/2002	Fujii	.....	H01L 33/486				
					438/26				
2009/0057855	A1 *	3/2009	Quinones	.....	H01L 23/49551				
					257/676				
2010/0059782	A1 *	3/2010	Fujitomo	.....	H01L 24/97				
					257/98				
2012/0132933	A1 *	5/2012	Watari	.....	H01L 33/52				
					257/88				

\* cited by examiner

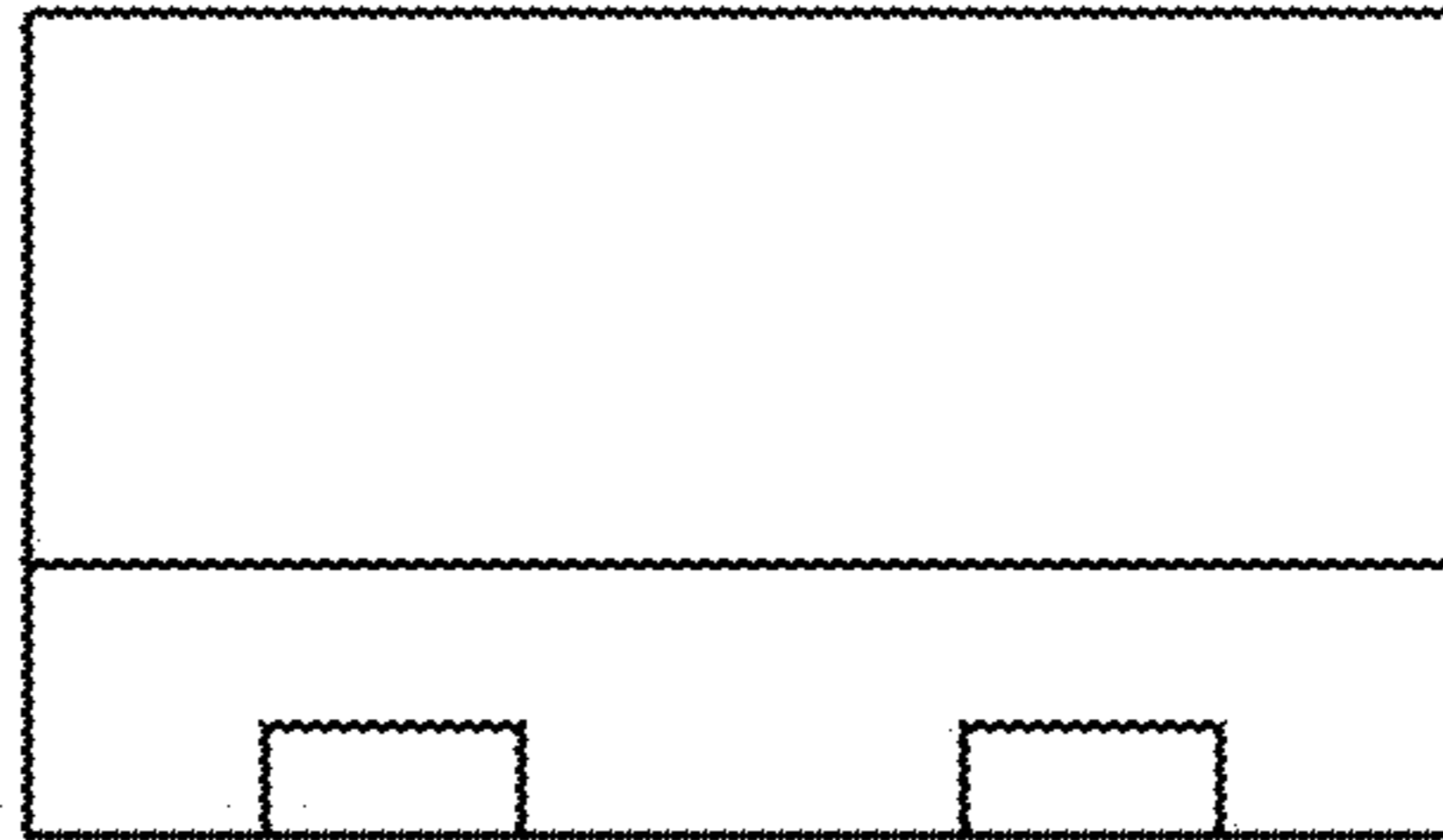


FIG. 1

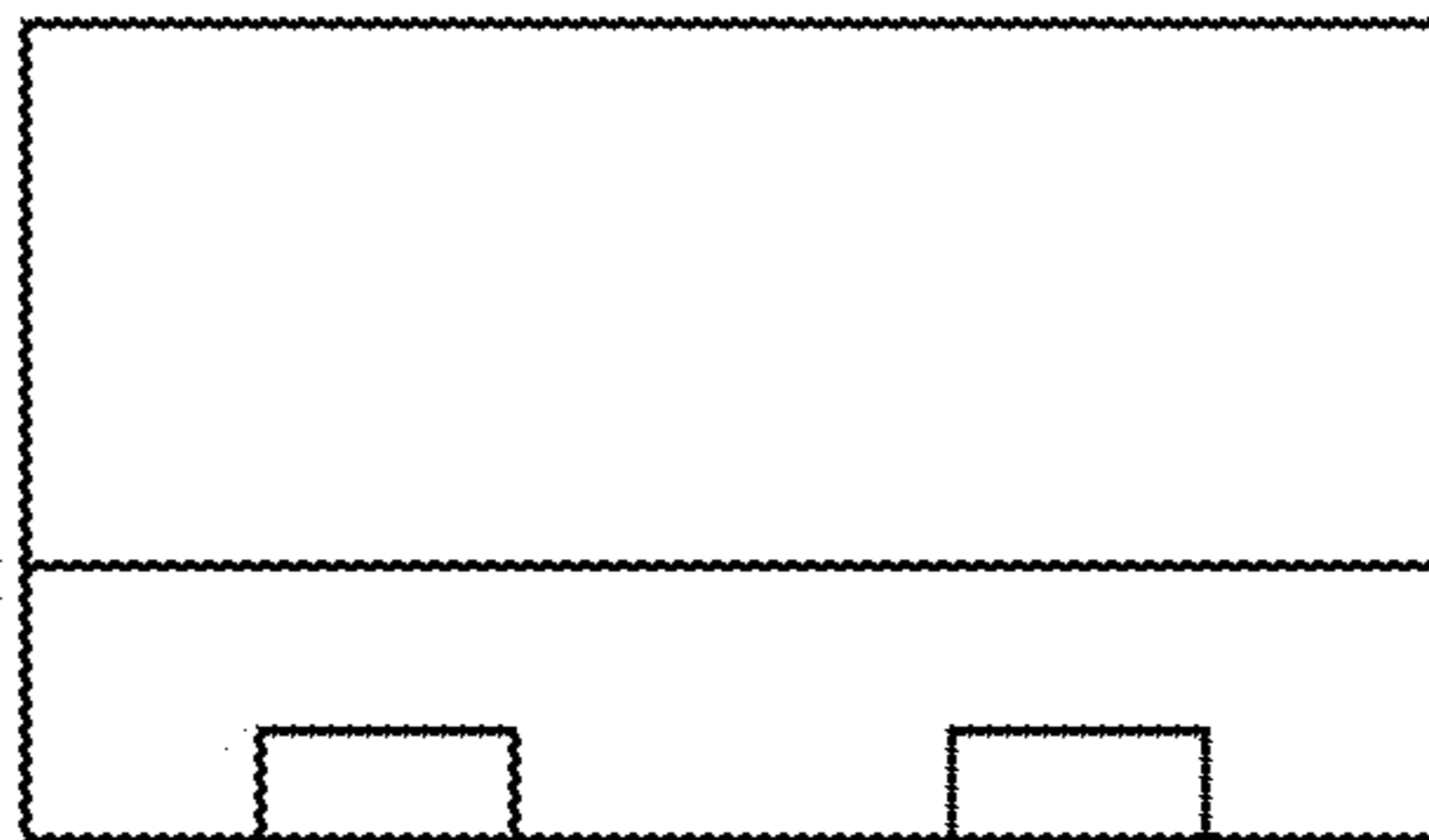


FIG. 2

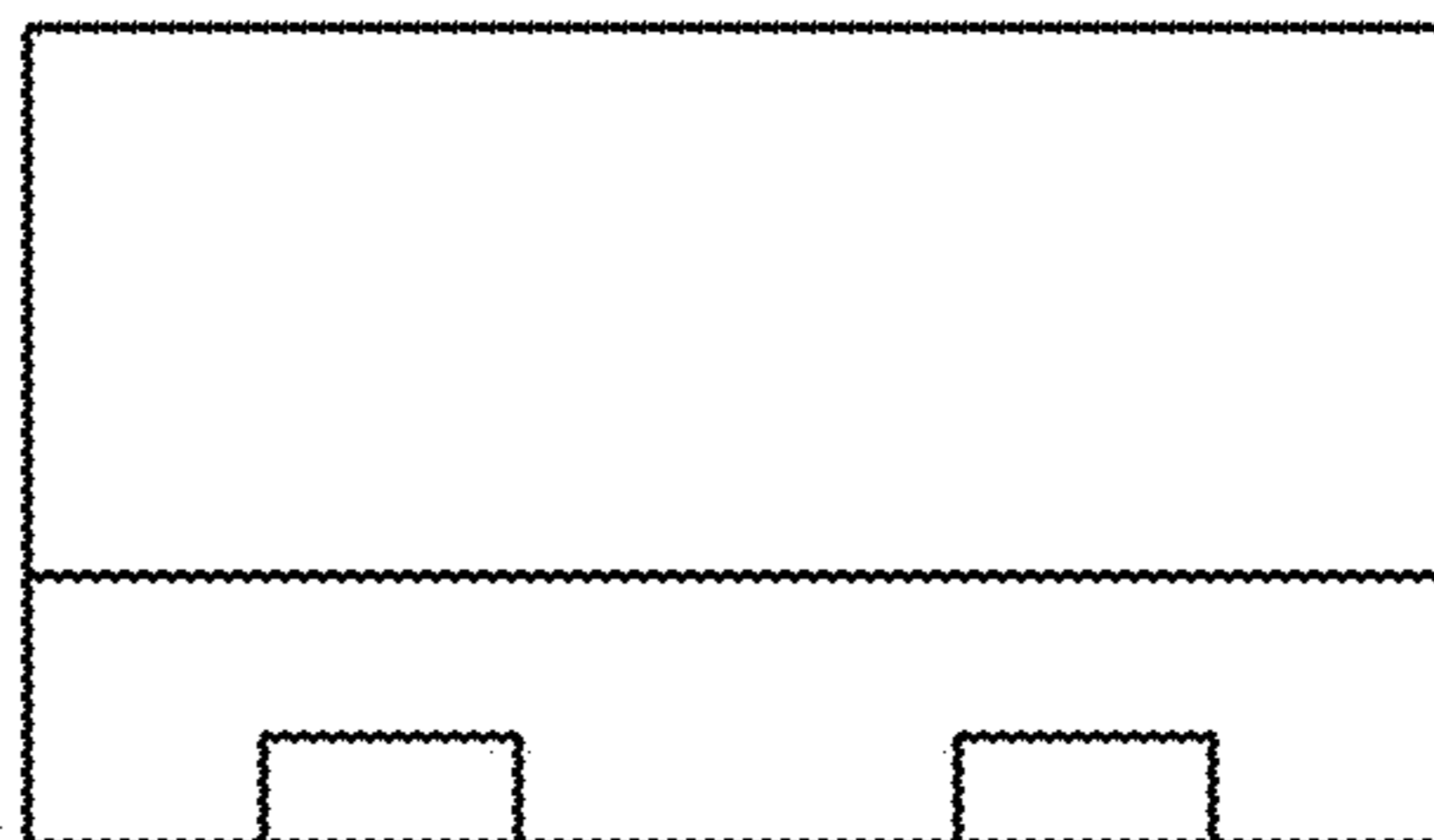


FIG. 3

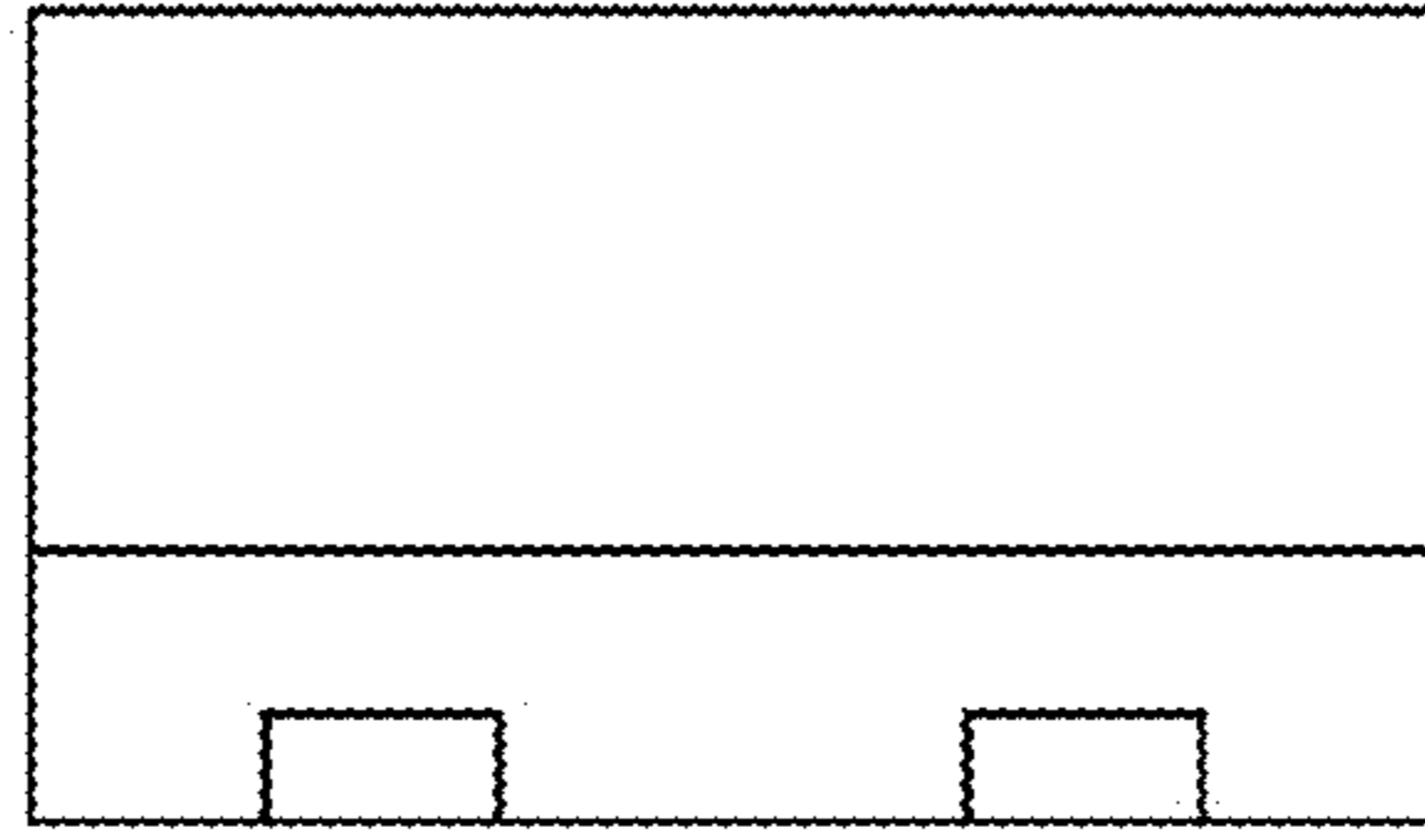


FIG. 4

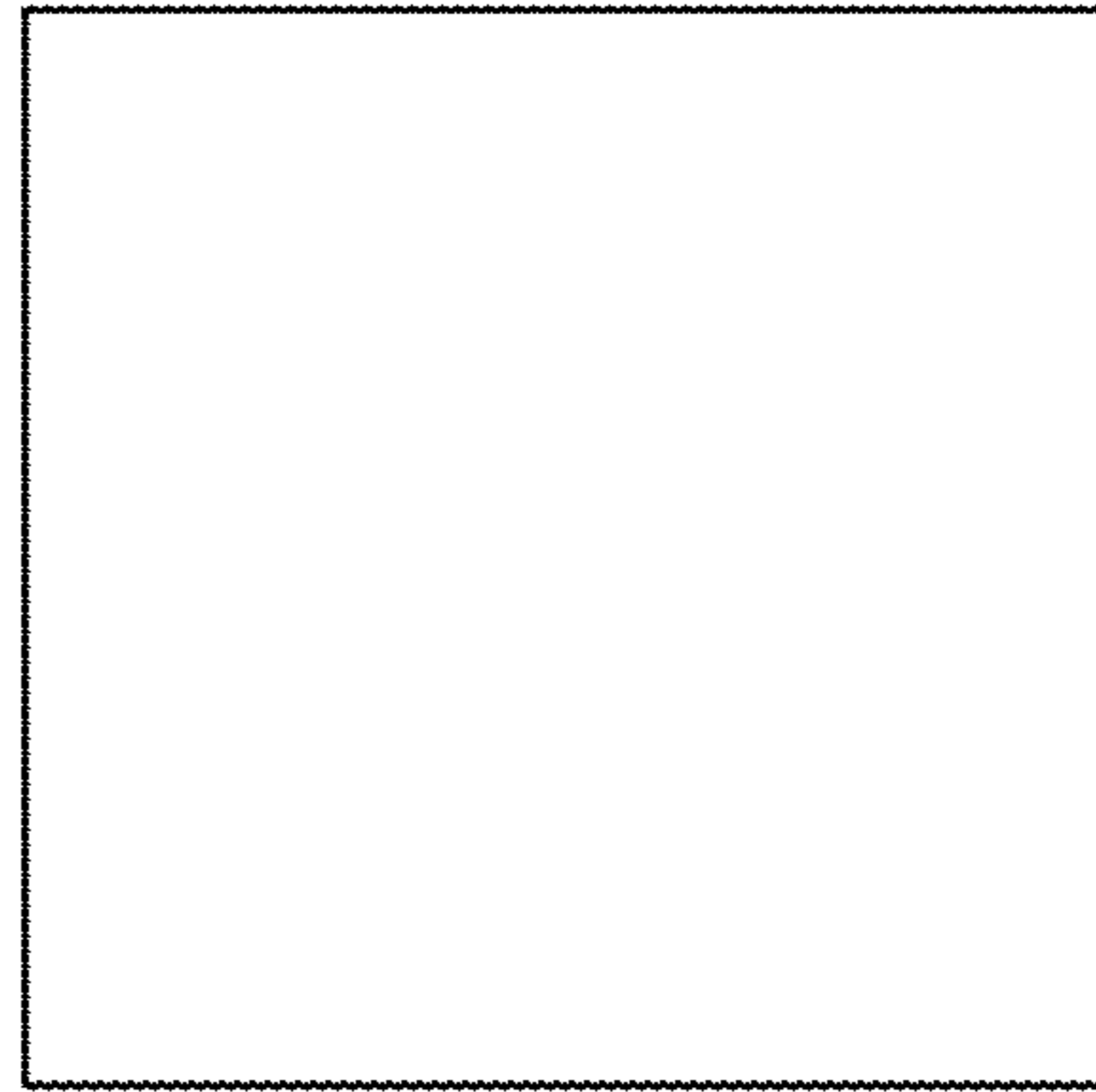


FIG. 5

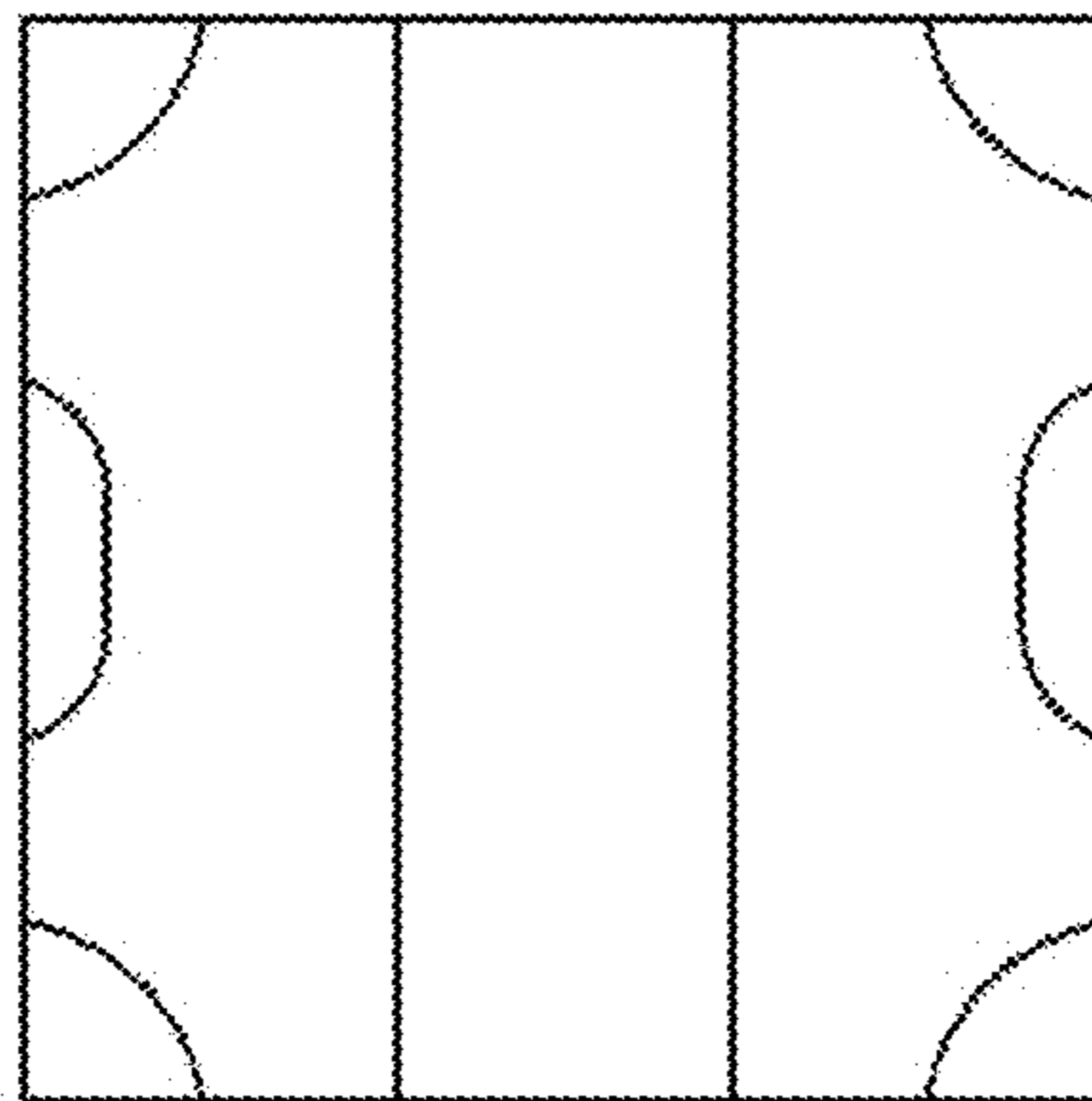


FIG. 6

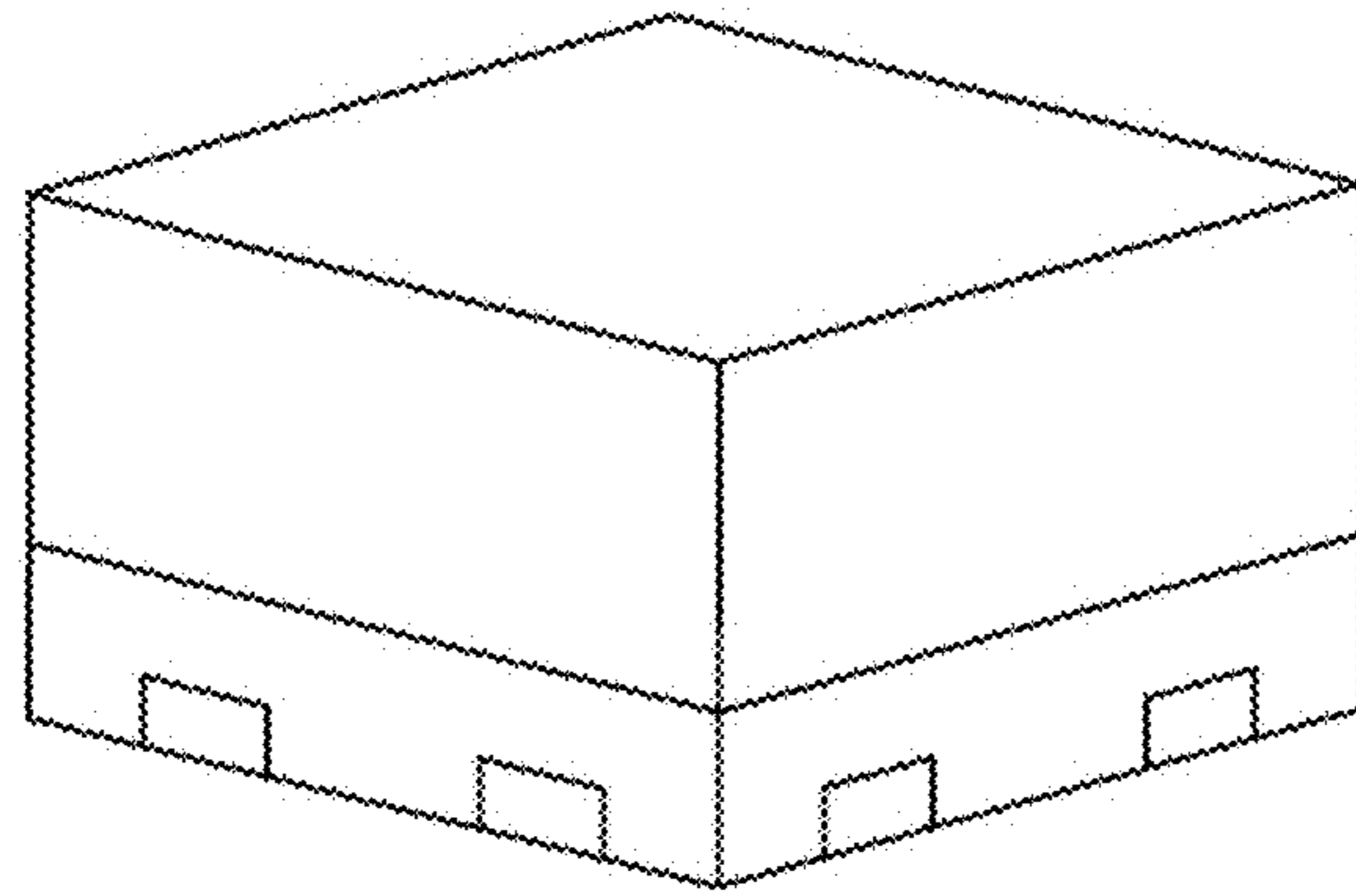


FIG. 7

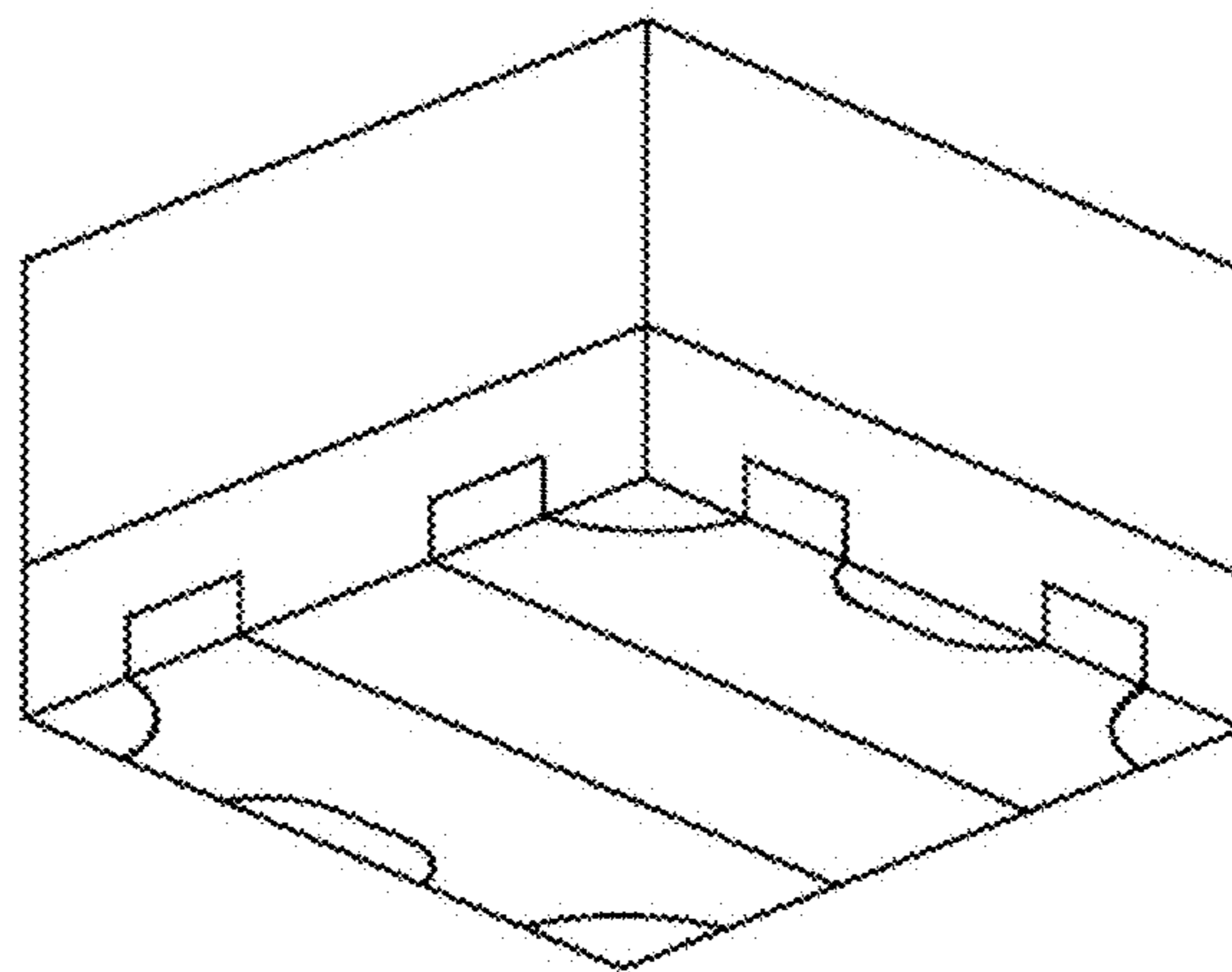


FIG. 8

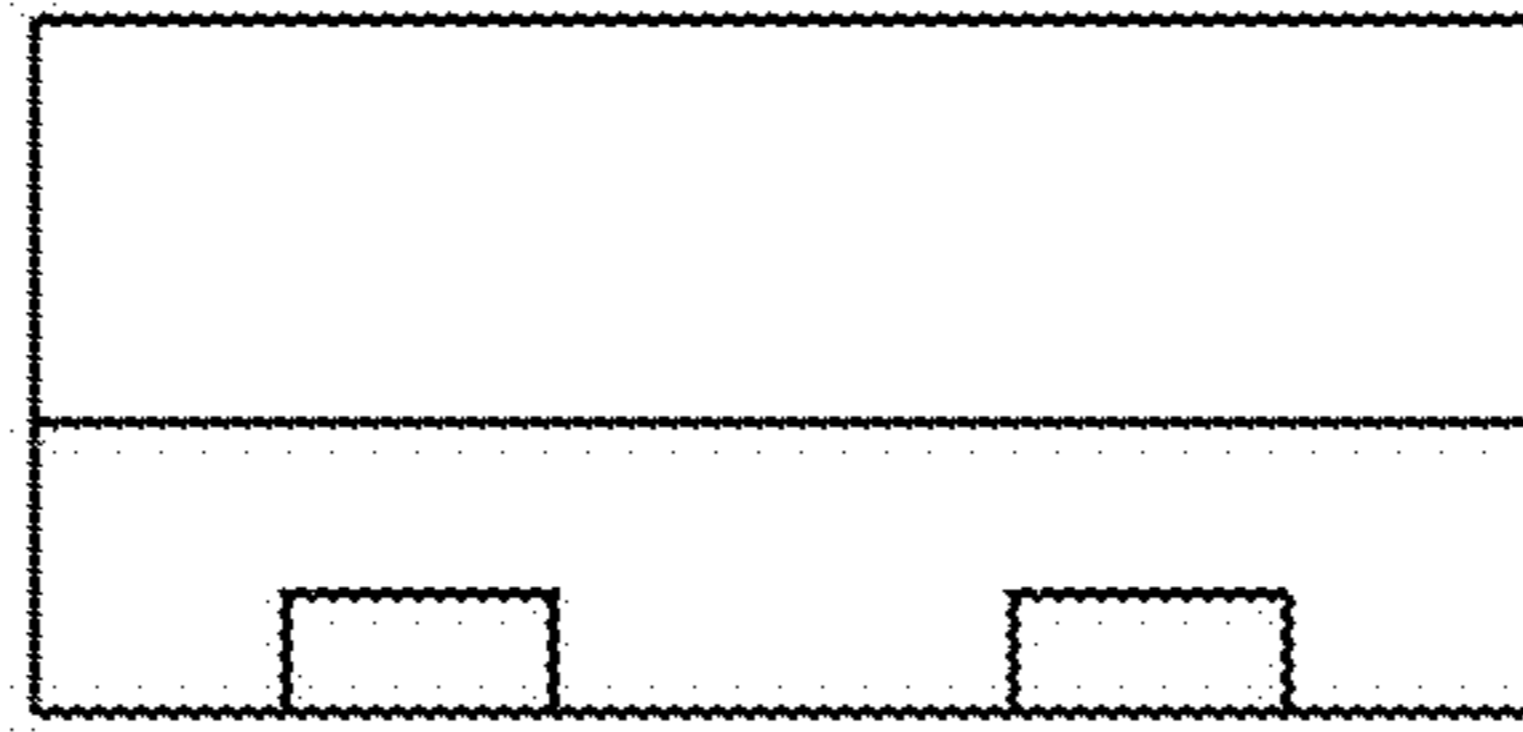


FIG. 9

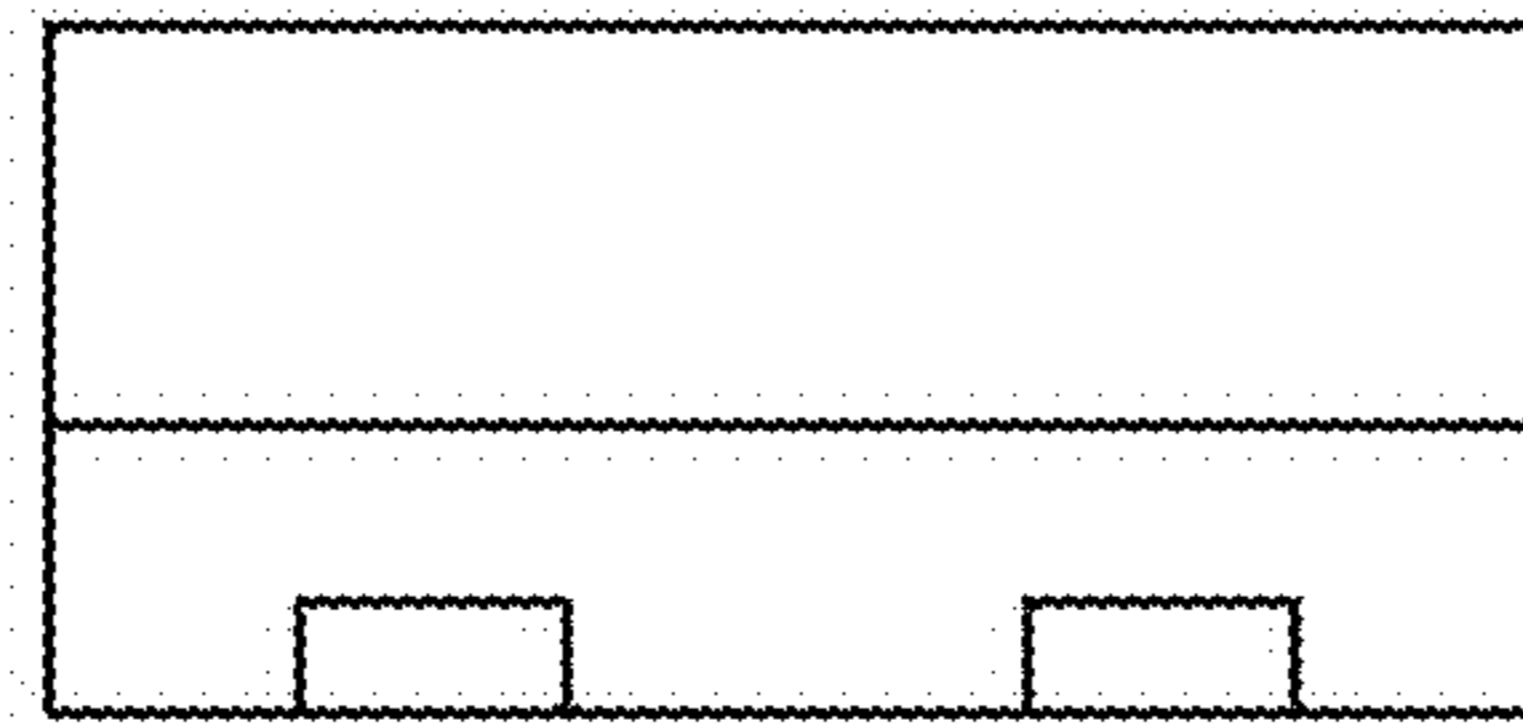


FIG. 10

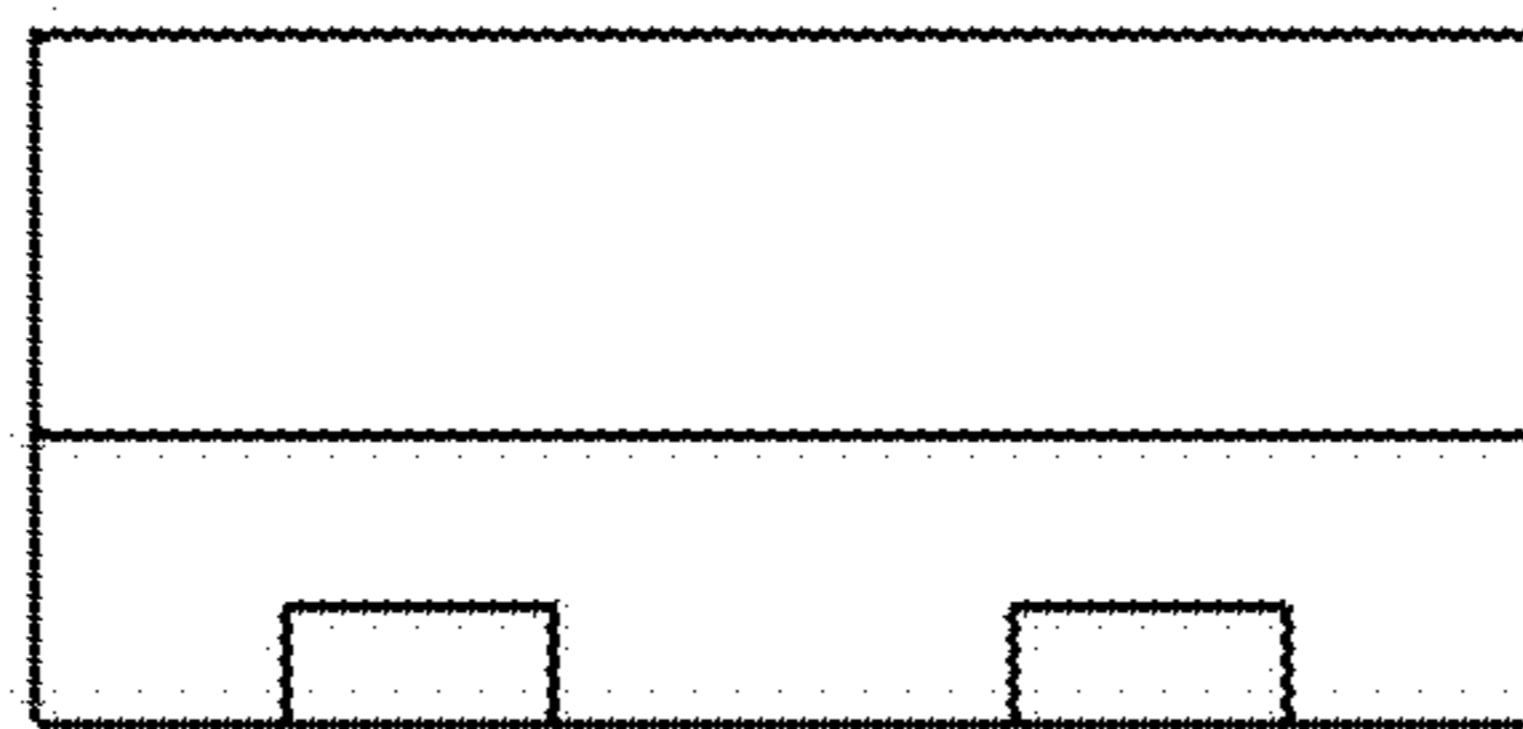


FIG. 11

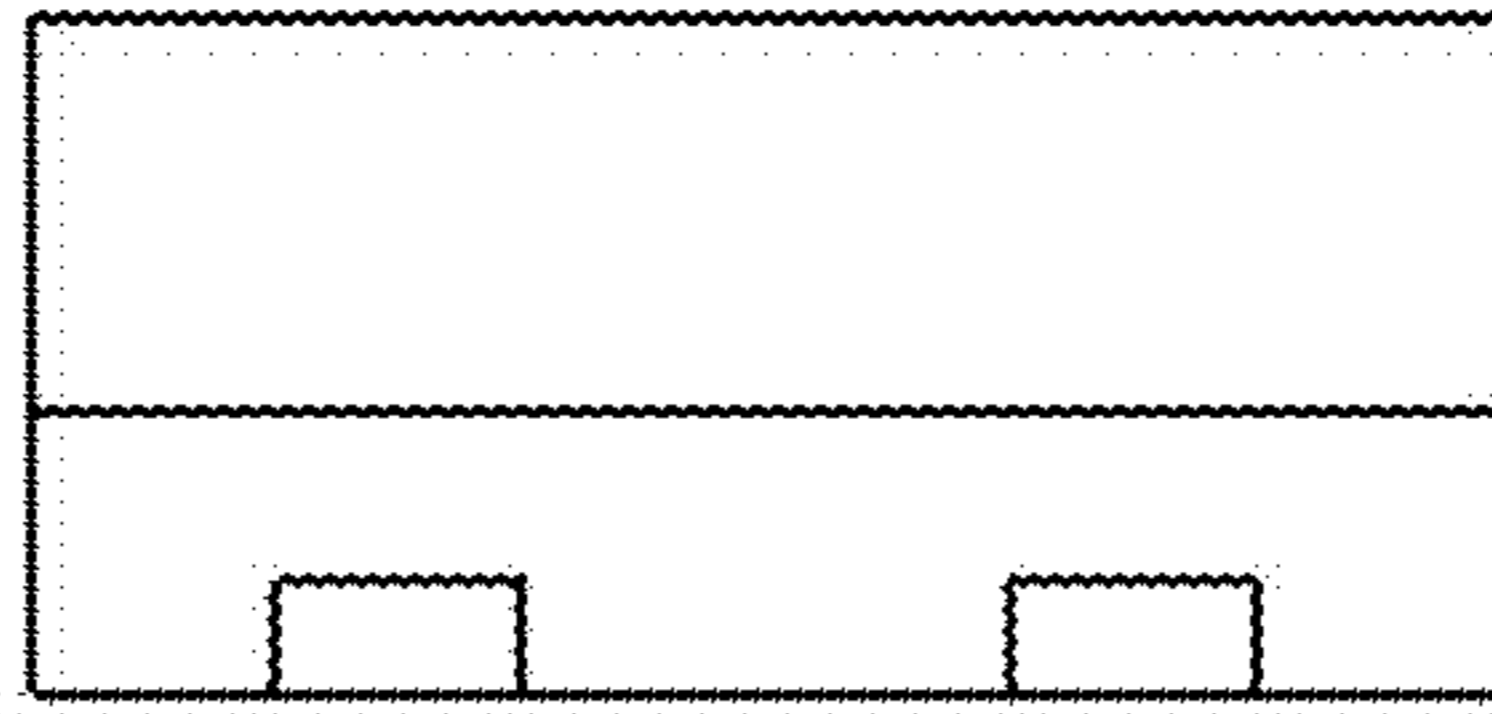


FIG. 12

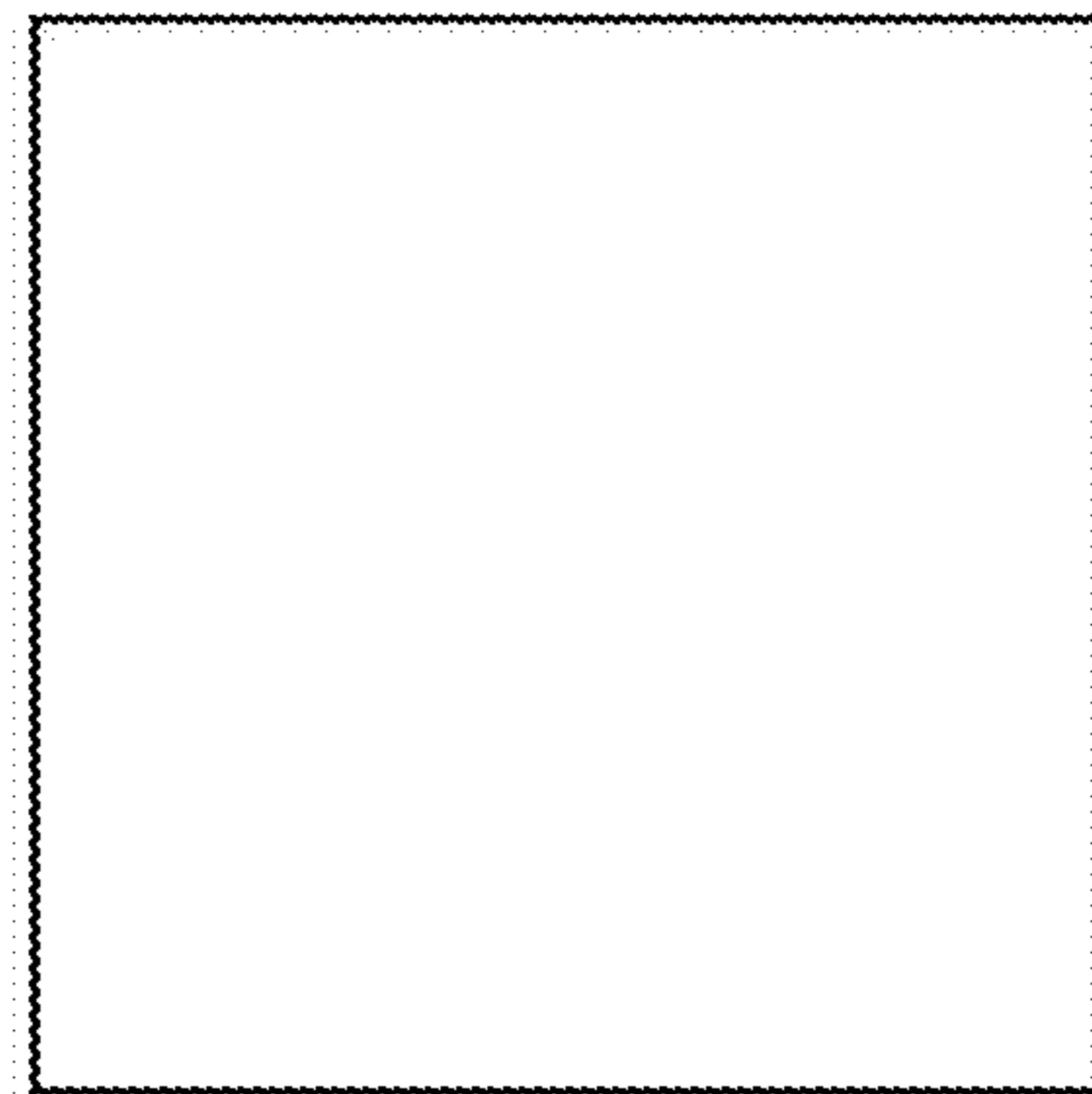


FIG. 13

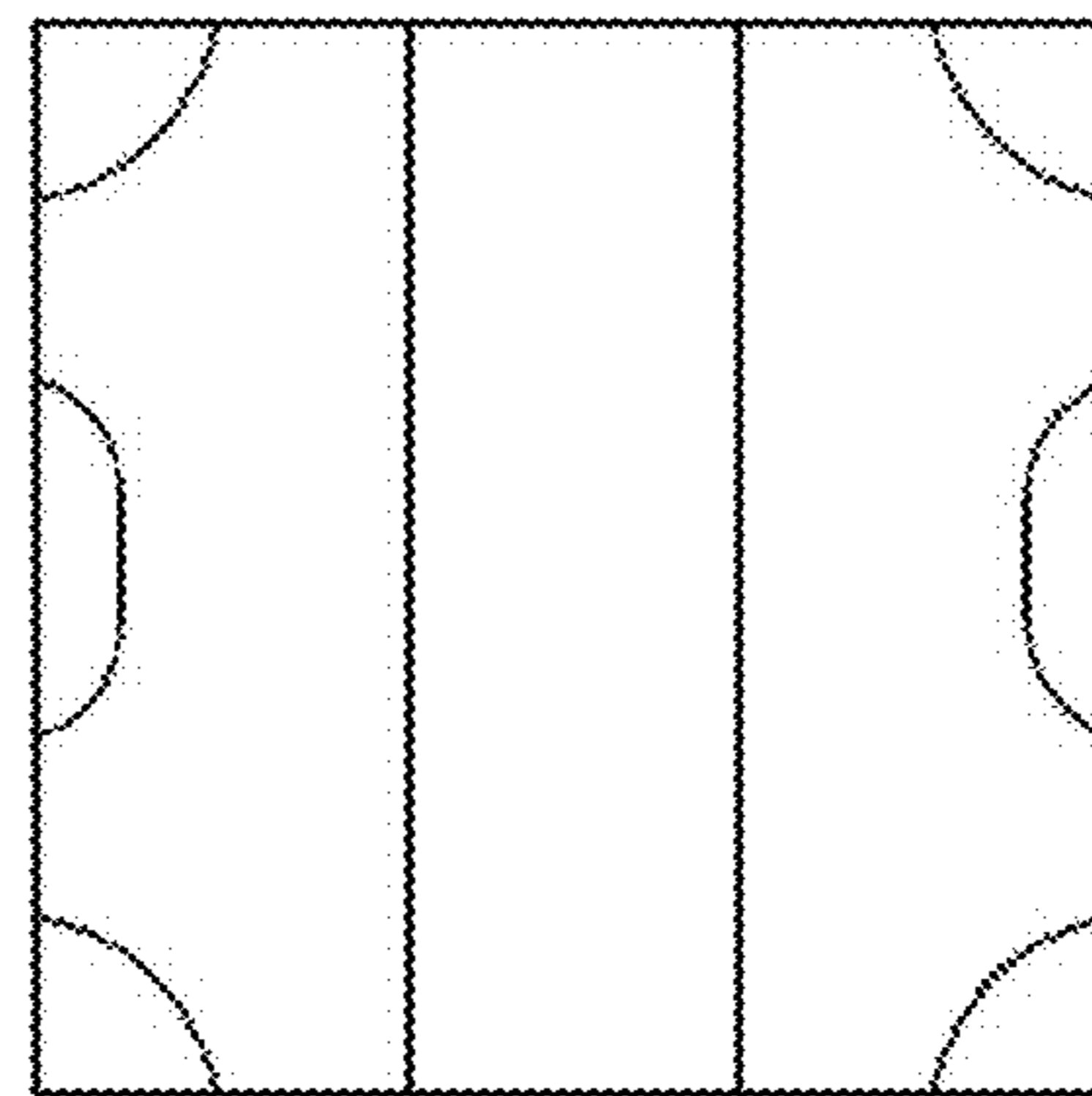


FIG. 14

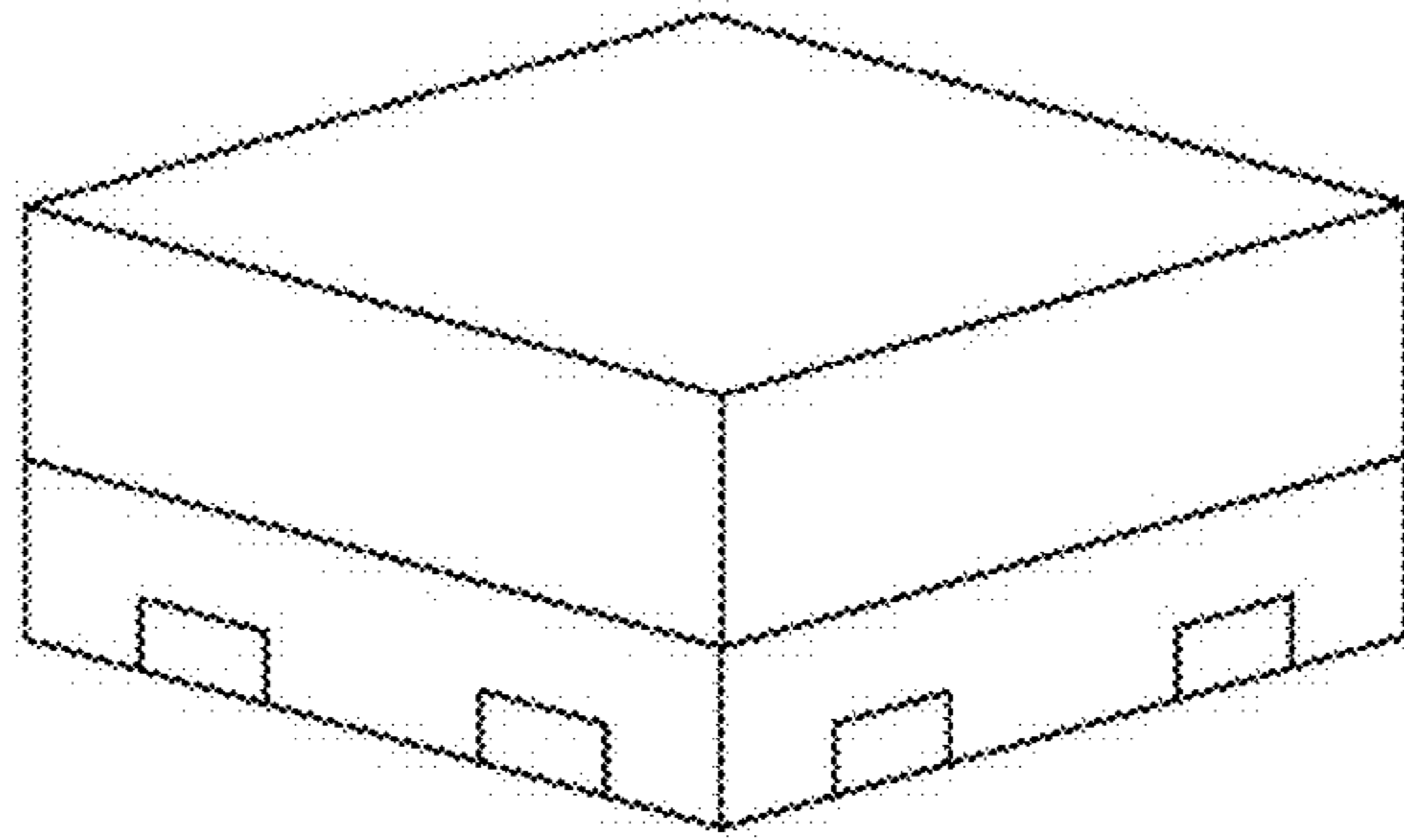


FIG. 15

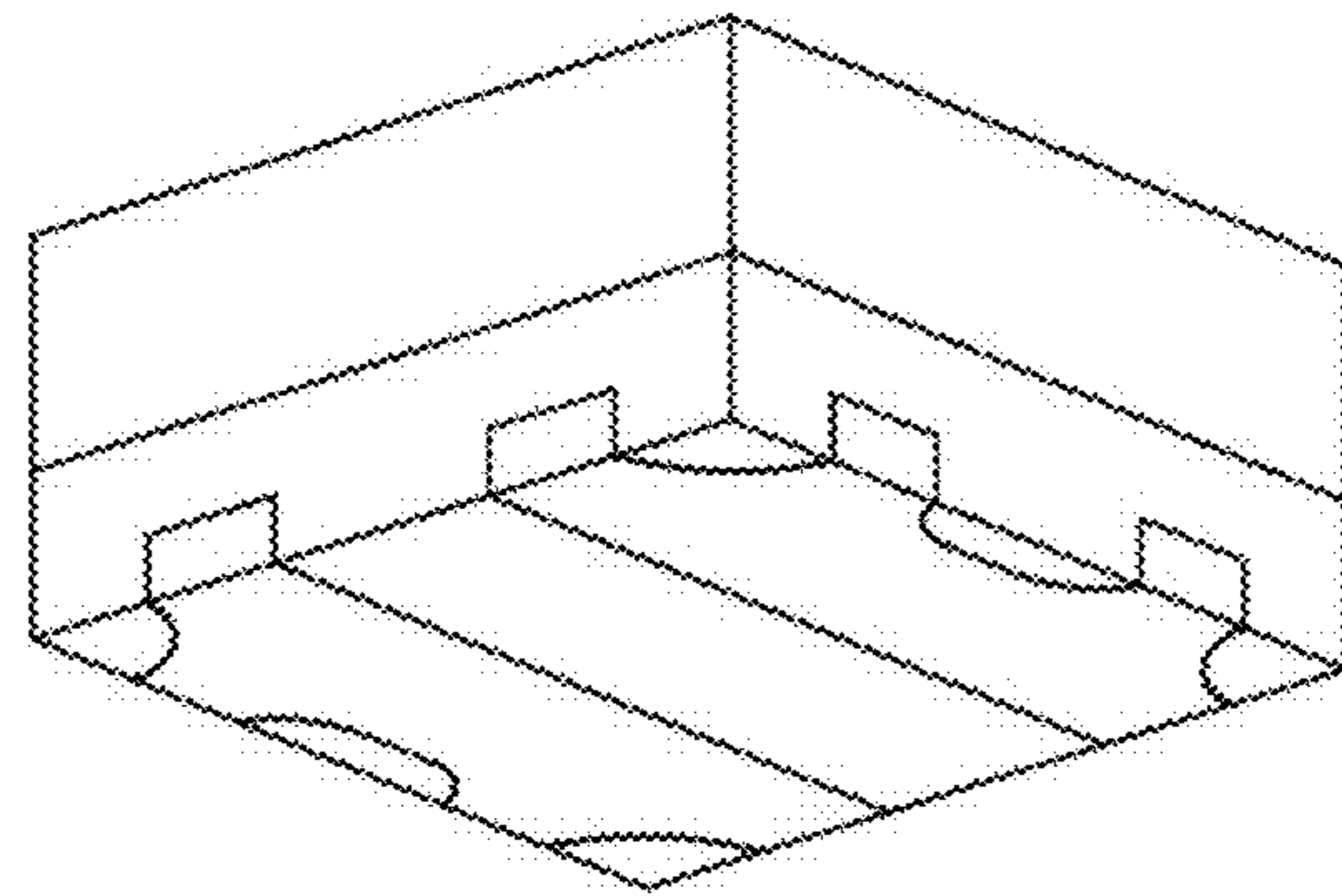


FIG. 16